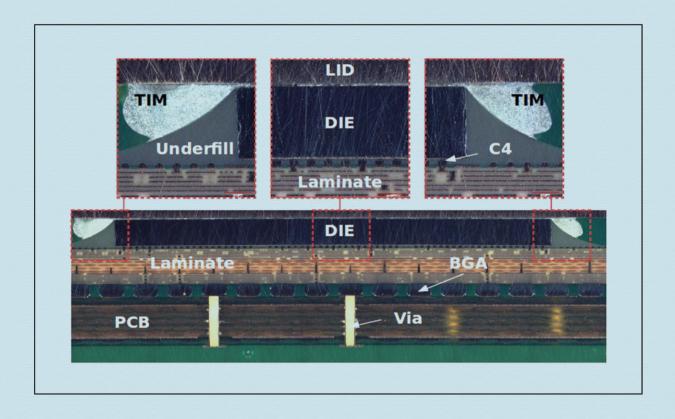


Journal of Electronics Cooling and Thermal Control





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ISSN 2162-6162 (print) ISSN 2162-6170 (online)

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ISSN Online: 2162-6170 ISSN Print: 2162-6162

June 2021

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Journal of Electronics Cooling and Thermal Control

ISSN 2162-6162 (print) ISSN 2162-6170 (online) https://www.scirp.org/journal/jectc

Journal of Electronics Cooling and Thermal Control (JECTC) is a quarterly, peer-reviewed, academic journal. It aims to provide a vehicle for the exchange and dissemination of original research results, technical notes, and state-of-the-art reviews pertaining to the electronic cooling and thermal system control technology in the computer and electronics industries.

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- Control scenario
- Electronics packaging
- Fan design and performance
- Forced convection heat transfer
- Heat storage
- Heat sink design and optimization
- High heat conductive materials
- Heat transfer in micro channels
- Insulation

- Interface thermal contact performance
- Natural convection heat transfer
- Phase changing heat transfer
- Phonon
- Radiation
- Spray cooling
- Temperature stability
- Thermal modeling of electronics systems and components

Technologies based on these transport processes such as

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- Various electronic devices, etc.

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